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SEMICONDUCTOR DEVICE AND ITS MANUFACTURE

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Applicant(s): SONY CORP
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Citation 1

Abstract

PURPOSE: To provide a semiconductor device and its manufacturing method capable of avoiding the decomposition of a reflection preventive film having stoichiometrically unstable bonds as well as forming a highly stable fine pattern.

CONSTITUTION: A reflection preventive film 12 having stoichiometrically unstable bonds is formed on an underneath substrate; a protective film 14 suppressing the change in the optical requirements of this reflection preventive film 12 is formed; and then a resist film is formed on this protective film 14 directly or through the intermediary of an interlayer film so as to be processed according to a specific pattern using photolithography.

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